BAS216WS

FEATURES

- For surface mounted applications
- Glass Passivated Chip Junction
- Fast reverse recovery time
- Ideal for automated placement
- Lead free in comply with EU RoHS 2011/65/EU directives

MECHANICAL DATA

- Case: SOD-323
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 5.48mg / 0.00019oz

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode

Top View MARKING:24

Simplified outline SOD-323 and symbol

Absolute Maximum Ratings at 25 °C

Parameter	Symbols	BAS216WS	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	250	V
Maximum RMS voltage	V_{RMS}	200	V
Continuous Forward Current	I_F	250	mA
Repetitive Peak Forward Current	I_{FRM}	625	mA
Non-reptitive Peak Forward Surge Current at 1s at 1ms at 1 us	I_{FSM}	1 3 9	A
Total Power Dissipation	P_{tot}	500	mW
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150	°C

Characteristics at T_a = 25 °C

Parameter	Symbols	BAS216WS	Units
Reverse BreakdownVoltage at I_R=100μA	$V_{(BR)R}$	250	V
Maximum Forward Voltage at 100 m A at 200 m A	V_F	1.00 1.25	V
Maximum DC Reverse Current T_a = 25 °C at Rated DC Blocking Voltage T_a =150 °C	I_R	0.1 100	μA
Typical Junction Capacitance at V_R=4V, f=1MHz	C_j	5	pF
Maximum Reverse Recovery Time (1)	t_{rr}	50	ns

(1) Measured with IF = 0.5 A, IR = 1 A, Irr = 0.25 A

Fig.1 Forward Current Derating Curve

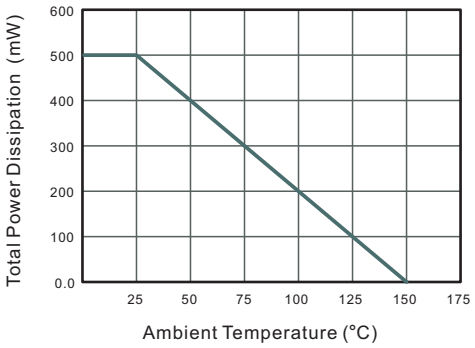


Fig.2 Typical Reverse Characteristics

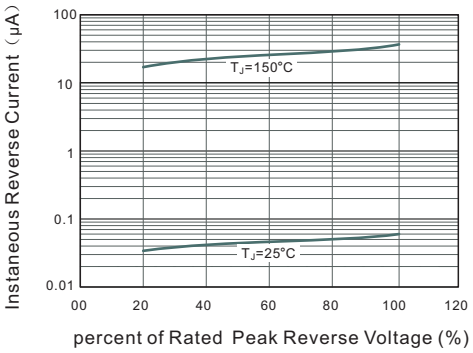


Fig.3 Typical Instaneous Forward Characteristics

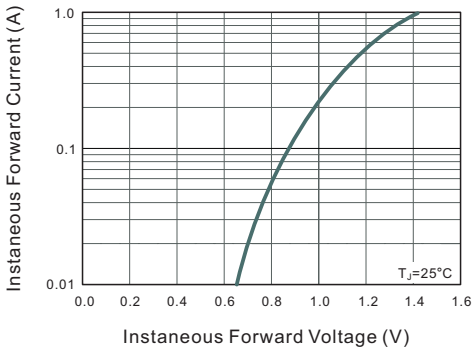
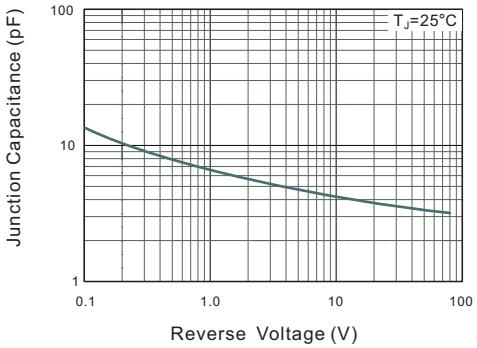


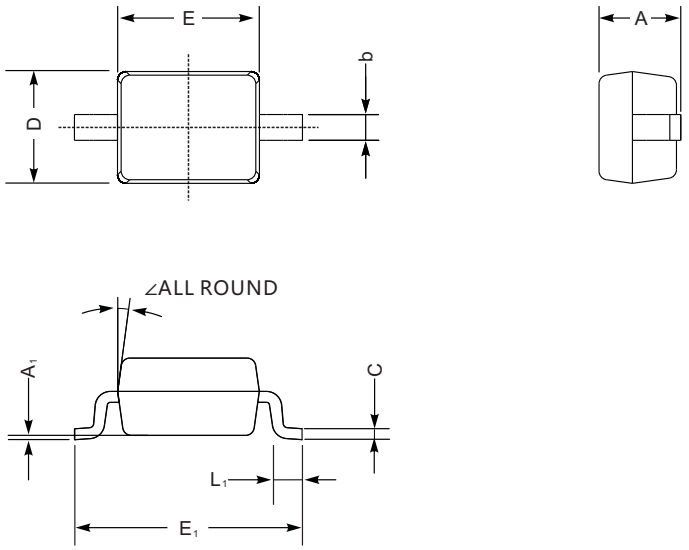
Fig.4 Typical Junction Capacitance



PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SOD-323



SOD-323 mechanical data

UNIT		A	C	D	E	E_1	b	L_1	A_1	∠
mm	max	1.1	0.15	1.4	1.8	2.75	0.4	0.45	0.2	9°
	min	0.8	0.08	1.2	1.4	2.55	0.25	0.2	—	
mil	max	43	5.9	55	70	108	16	16	8	
	min	32	3.1	47	63	100	9.8	7.9	—	

The recommended mounting pad size